

### **Supplementary Information**

#### **Ferroelectric Memristors Optimized in Thickness for Short-Term Memory-Driven Reservoir Computing**

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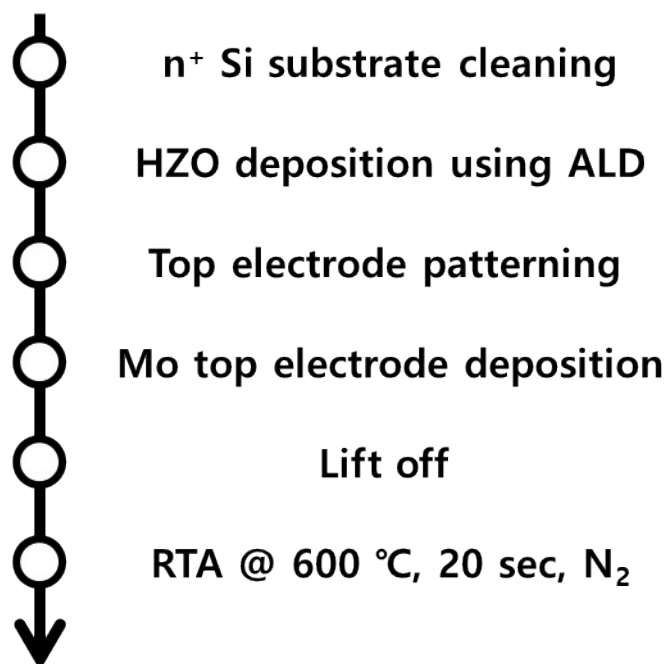
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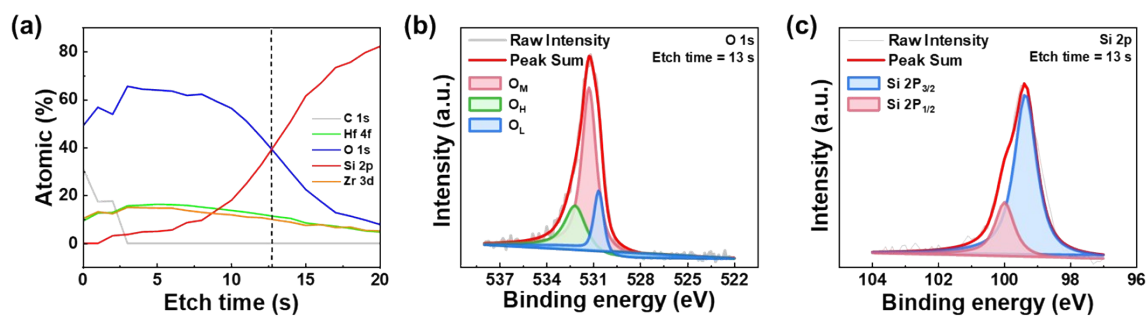
#### **\* Corresponding author:**

Sungjun Kim (Email: [sungjun@dongguk.edu](mailto:sungjun@dongguk.edu))

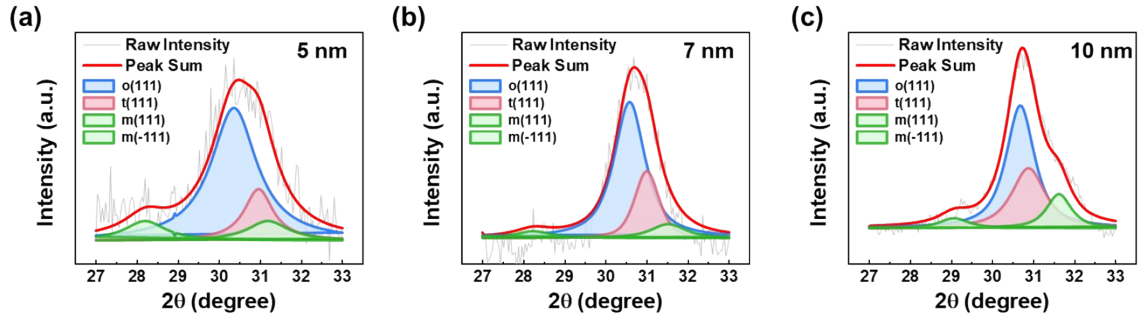
Supplementary figures



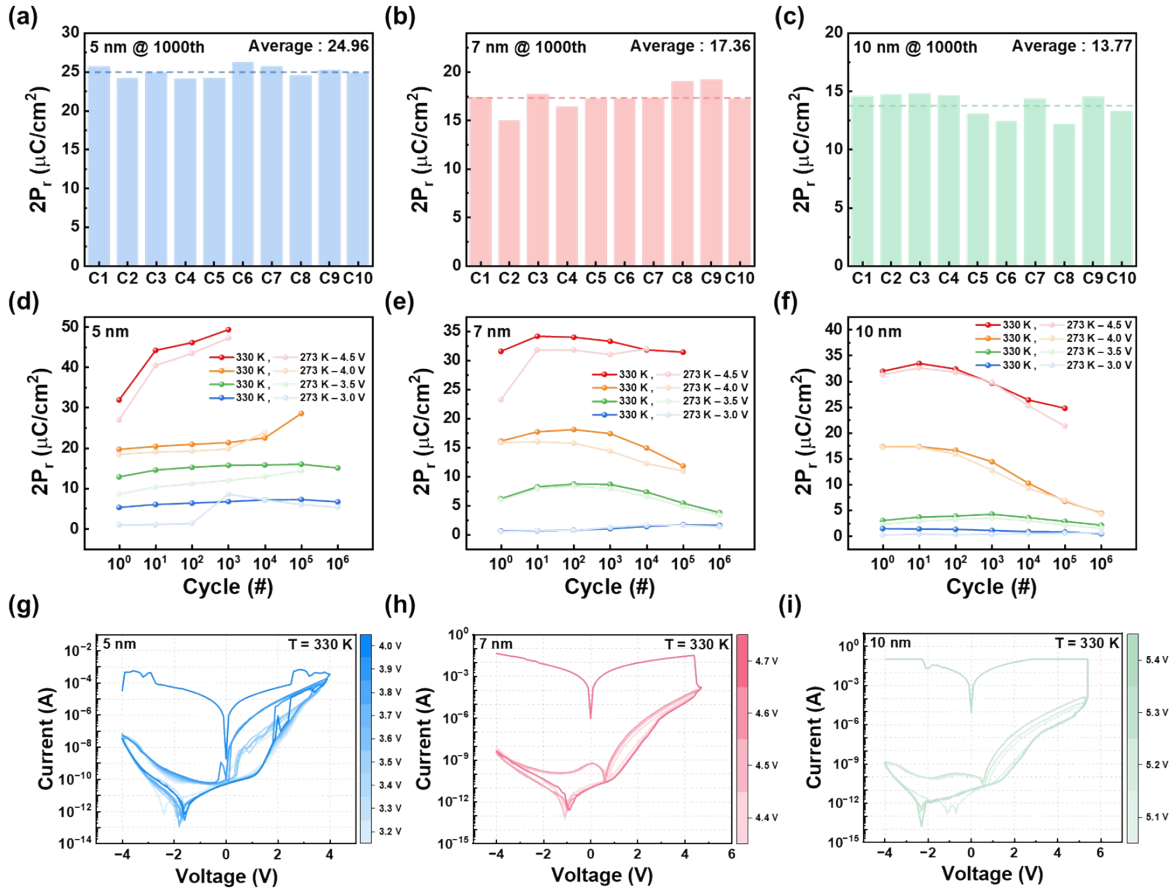
**Figure S1.** Fabrication process of the Mo/HZO/n<sup>+</sup> Si device.



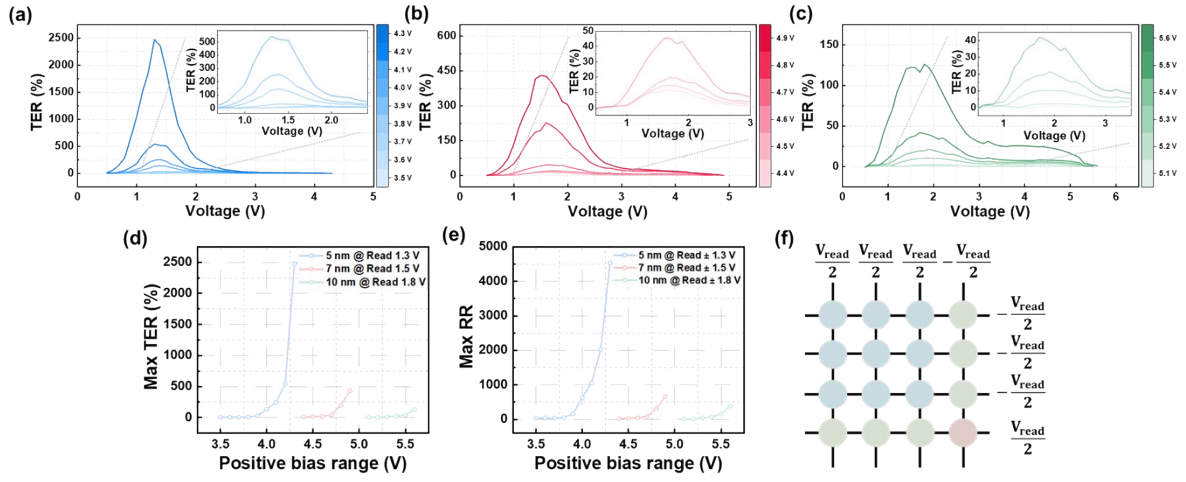
**Figure S2.** (a) Elemental composition as a function of etching time. (b) XPS peak spectra representing (b) O 1s and (c) Si 2p of the SiO<sub>2</sub> layer.



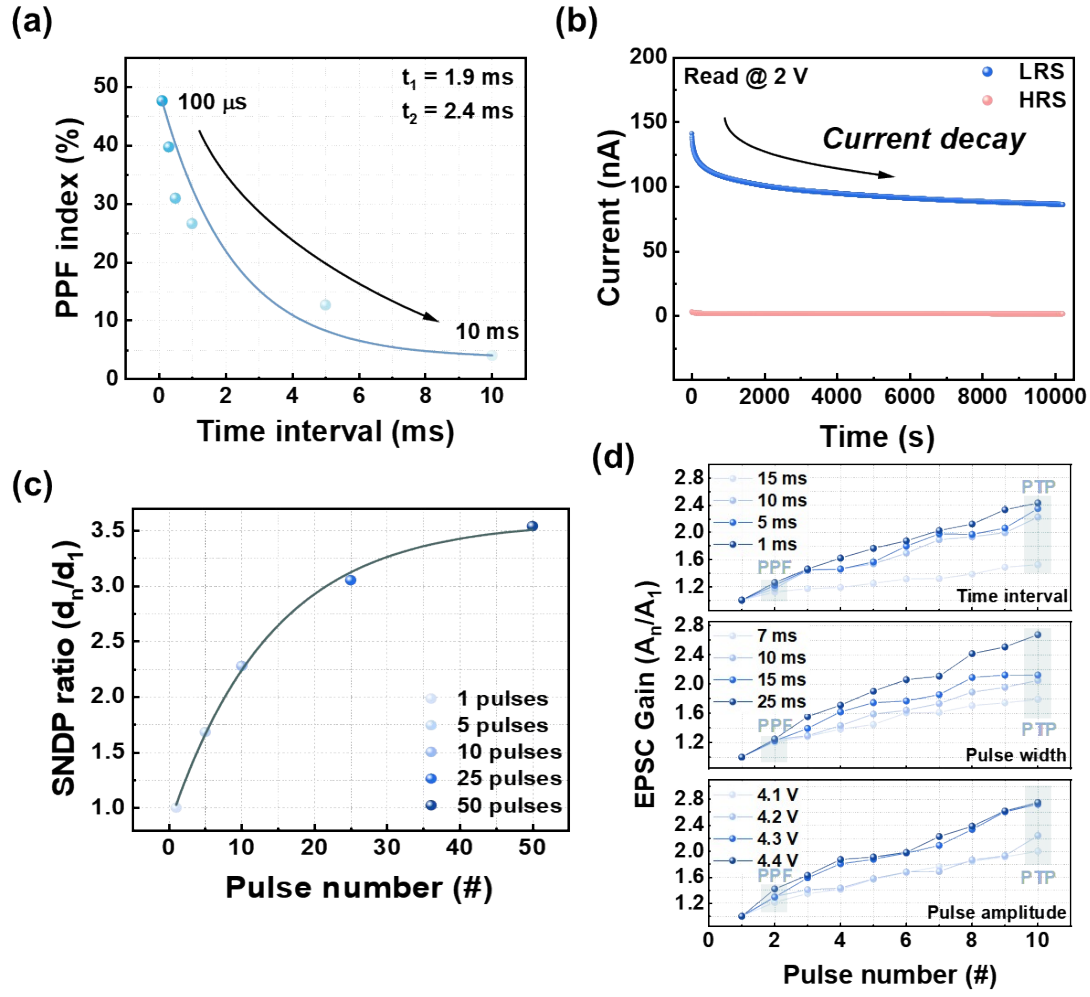
**Figure S3.** Deconvoluted GIXRD spectra of the devices with HZO film thickness of (a) 5 nm, (b) 7 nm, (c) 10 nm.



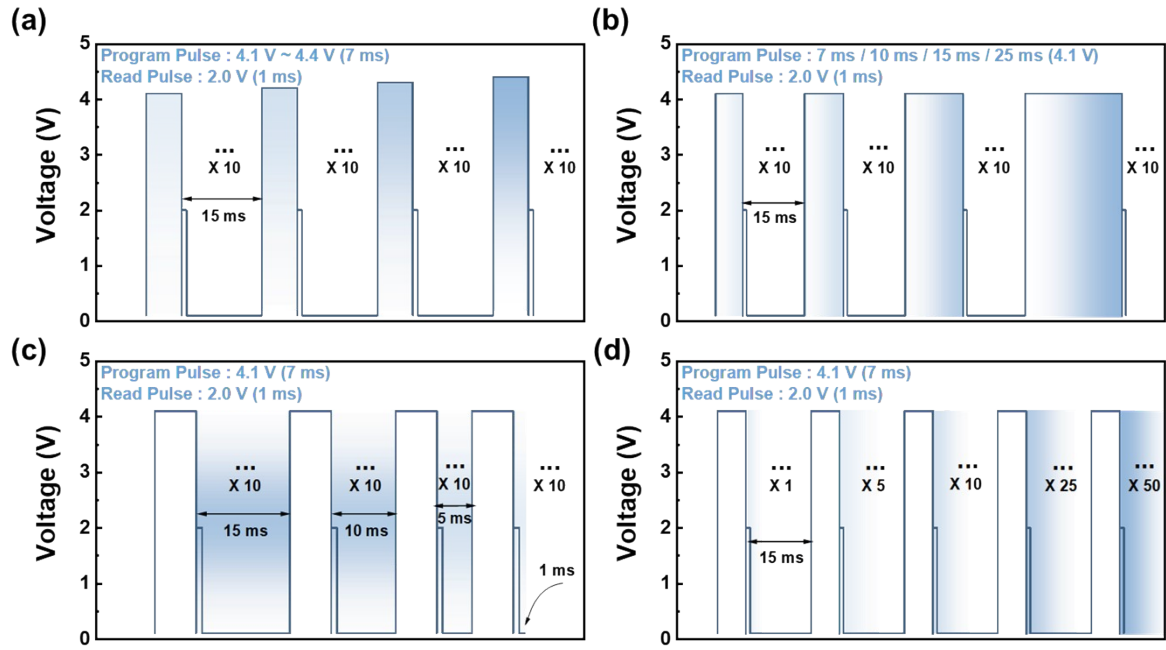
**Figure S4.** Cell-to-cell variation of  $2P_r$  values for devices with HZO thicknesses of (a) 5 nm, (b) 7 nm, and (c) 10 nm. Endurance characteristics measured at 273 K and 330 K for HZO thicknesses of (d) 5 nm, (e) 7 nm, and (f) 10 nm. Current–voltage (I–V) characteristics measured at 330 K for HZO thicknesses of (g) 5 nm, (h) 7 nm, and (i) 10 nm.



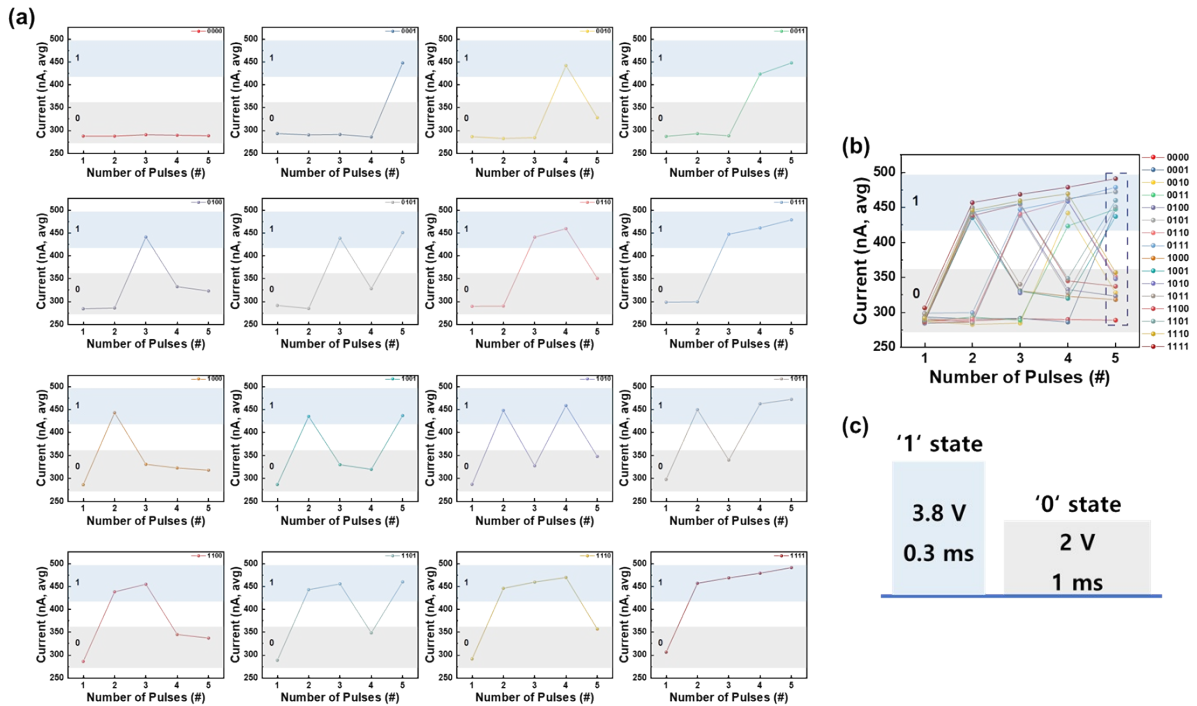
**Figure S5.** Maximum TER as a function of voltage for devices with HZO thicknesses of (a) 5 nm, (b) 7 nm, and (c) 10 nm. Bias-dependent values of (d) Max TER and (e) Max RR for each device. (f) The modified half-bias scheme.



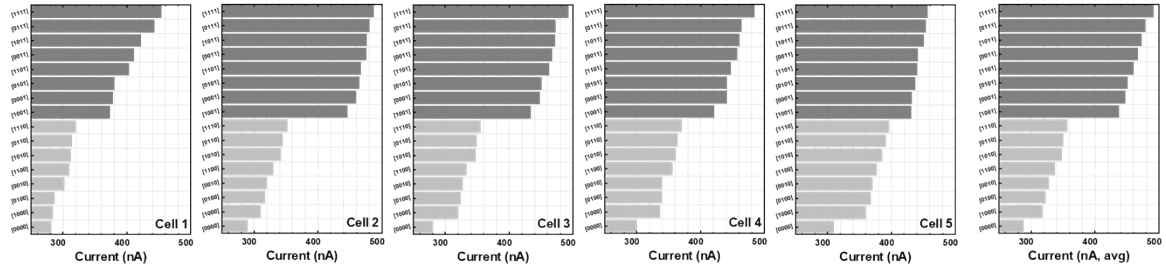
**Figure S6.** (a) PPF index as a function of spike interval between two pulses and the time decay constants. (b) Retention characteristics at a read voltage of 2 V over 10,000 s. (c) SNRP ratio. (d) SRDP, SDDP, SADP gain.



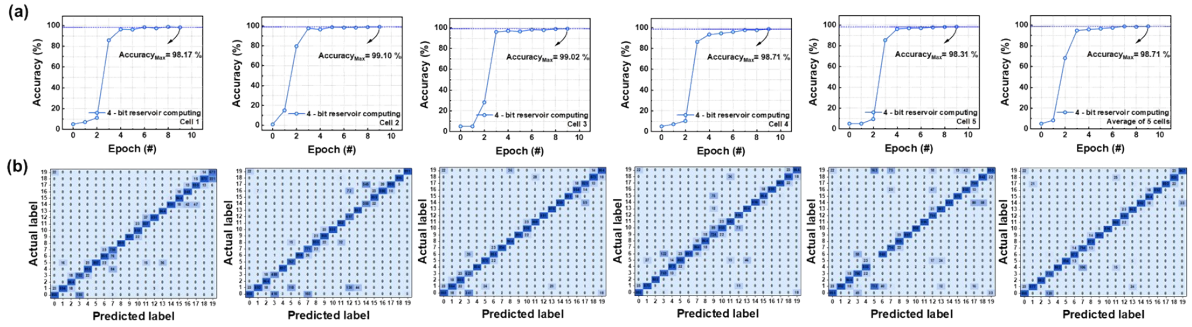
**Figure S7.** Pulse schemes used to verify the characteristics of (a) SADP, (b) SWDP, (c) SRDP, and (d) SNDP.



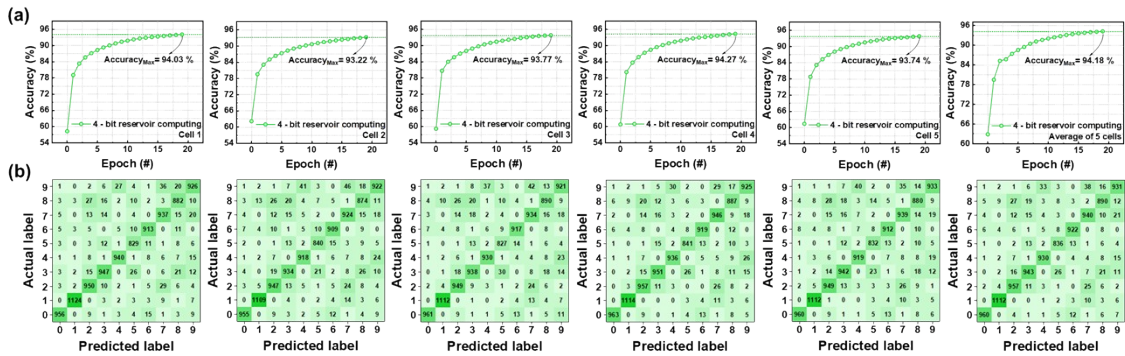
**Figure S8.** (a) 16 different four-bit states, each measured from a single cell. (b) Pulse schemes for the '1' and '0' states. (c) Average current levels of 16 four-bit states in the short-term memory device, obtained by averaging over five cells.



**Figure S9.** Separation characteristics of reservoir states obtained from each cell and averaging.

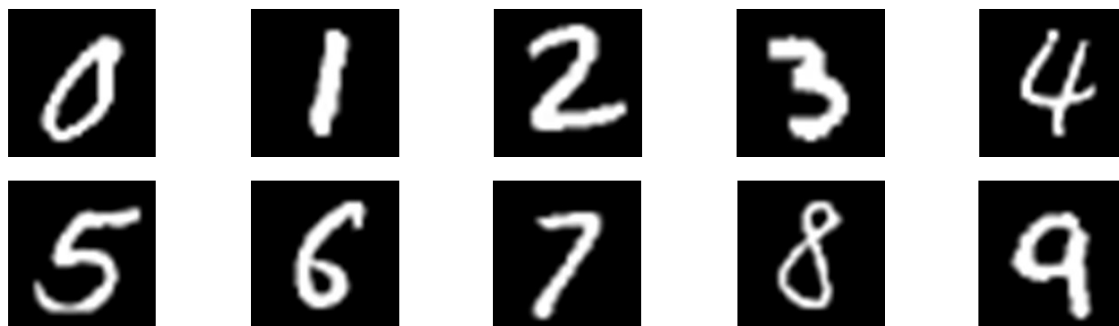


**Figure S10.** (a) Pattern recognition accuracy of the Hand MNIST device, measured for each cell. (b) Confusion matrix of Hand MNIST recognition using a 4-bit model with diagonal weights, measured for each cell.



**Figure S11.** (a) Pattern recognition accuracy of the MNIST device, measured for each cell. (b) Confusion matrix of MNIST digit recognition using a 4-bit model with diagonal weights, measured for each cell.

(a)



(b)



**Figure S12.** Sample images from (a) MNIST, (b) Hand MNIST datasets.